## General Description

The 843252-45 is a 2 LVPECL output Synthesizer optimized to generate Ethernet reference clock frequencies. Using a 25MHz, 18pF parallel resonant crystal, the following frequencies can be generated: 156.25MHz and 125MHz. The 843252-45 uses IDT's 3rd generation low phase noise VCO technology and can achieve 1ps or lower typical rms phase jitter, easily meeting Ethernet jitter requirements. The 843252-45 is packaged in a small 16-pin TSSOP package.

Features

- Two differential LVPECL output pairs
- Crystal oscillator interface designed for a 25MHz, 18pF parallel resonant crystal
- A 25MHz crystal generates output frequencies of: 156.25MHz and 125MHz
- VCO frequency: 625MHz
- RMS Phase Jitter @ 156.25MHz, (1.875MHz – 20MHz) using a 25MHz crystal: 0.54ps (typical)
- Full 3.3V supply mode
- 0°C to 70°C ambient operating temperature
- Available in lead-free (RoHS 6) package
- For functional replacement part us 8T49N241

Block Diagram
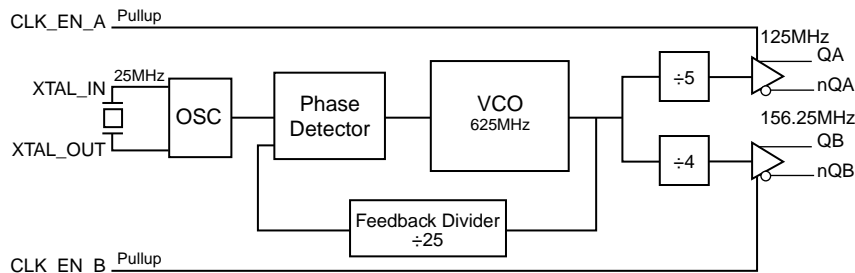
Pin Assignment

843252-45

16-Lead TSSOP
4.4mm x 5.0mm x 0.925mm package body
G Package

Table 1. Pin Descriptions

Number	Name	Type		Description
1	CLK_EN_A	Input	Pullup	Output enable pin. LVCMOS/LVTTL interface levels. See Table 3A.
2, 9, 15	V_{EE}	Power		Negative supply pins.
3, 4	QA, nQA	Output		Differential output pair. LVPECL interface levels.
5	V_{CCOA}	Power		Output supply pin for QA/nQA outputs.
6	nc	Unused		No connect.
7	V_{CCA}	Power		Analog supply pin.
8	V_{CC}	Power		Power supply pin.
10 11	XTAL_OUT XTAL_IN	Input		Crystal oscillator interface XTAL_IN is the input, XTAL_OUT is the output.
12	V_{CCOB}	Power		Output supply pin for QB/nQB outputs.
13, 14	nQB, QB	Output		Differential output pair. LVPECL interface levels.
16	CLK_EN_B	Input	Pullup	Output enable pin. LVCMOS/LVTTL interface levels. See Table 3B.

NOTE: *Pullup* refers to internal input resistors. See Table 2, *Pin Characteristics,* for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ

Function Tables

Table 3A. CLK_EN_A Function Table

Input	Outputs	
CLK_EN_A	QA	nQA
0	LOW	HIGH
1 (default)	Active	Active

Table 3B. CLK_EN_B Function Table

Input	Outputs	
CLK_EN_B	QB	nQB
0	LOW	HIGH
1 (default)	Active	Active

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Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device.
These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond
those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for
extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to V_{CC} + 0.5V
Outputs, I_O Continuos Current Surge Current	50mA 100mA
Package Thermal Impedance, θ_{JA}	92.4°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{CC} = V_{CCOA} = V_{CCOB} = 3.3V \pm 5\%$, $T_A = 0°C$ to $70°C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Power Supply Voltage		3.135	3.3	3.465	V
V_{CCA}	Analog Supply Voltage		$V_{CC} - 0.15$	3.3	V_{CC}	V
$V_{CCOA,}$ V_{CCOB}	Power Supply Voltage		3.135	3.3	3.465	V
I_{CCA}	Analog Supply Current				15	mA
I_{EE}	Power Supply Current				75	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{CC} = V_{CCOA} = V_{CCOB} = 3.3V \pm 5\%$, $T_A = 0°C$ to $70°C$

Symbol	Parameter	Test Conditions		Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage			2		V_{CC} + 0.3	V
V_{IL}	Input Low Voltage			-0.3		0.8	V
I_{IH}	Input High Current	CLK_EN_A, CLK_EN_B	$V_{CC} = V_{IN} = 3.465V$			5	µA
I_{IL}	Input Low Current	CLK_EN_A, CLK_EN_B	$V_{CC} = 3.465V$, $V_{IN} = 0V$	-150			µA

Table 4C. LVPECL DC Characteristics, $V_{CC} = V_{CCOA} = V_{CCOB} = 3.3V \pm 5\%$, $T_A = 0°C$ to $70°C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CCO} - 1.4$		$V_{CCO} - 0.9$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CCO} - 2.0$		$V_{CCO} - 1.7$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Output termination with 50Ω to $V_{CCOA,B} - 2V$.

Table 5. Crystal Characteristics

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency			25		MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance				7	pF

NOTE: Characterized using an 18pF parallel resonant crystal.

AC Electrical Characteristics

Table 6. AC Characteristics, $V_{CC} = V_{CCOA} = V_{CCOB} = 3.3V \pm 5\%$, $T_A = 0°C$ to $70°C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency	QA/nQA			125		MHz
		QB/nQB			156.25		MHz
$f_{jit(\varnothing)}$	RMS Phase Jitter (Random); NOTE 1		125MHz, Integration Range: 1.875MHz – 20MHz		0.56		ps
			156.25MHz, Integration Range: 1.875MHz – 20MHz		0.54		ps
t_R / t_F	Output Rise/Fall Time		20% to 80%	300		700	ps
odc	Output Duty Cycle			49		51	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. Device will meet specifications after thermal equilibrium has been reached under these conditions.
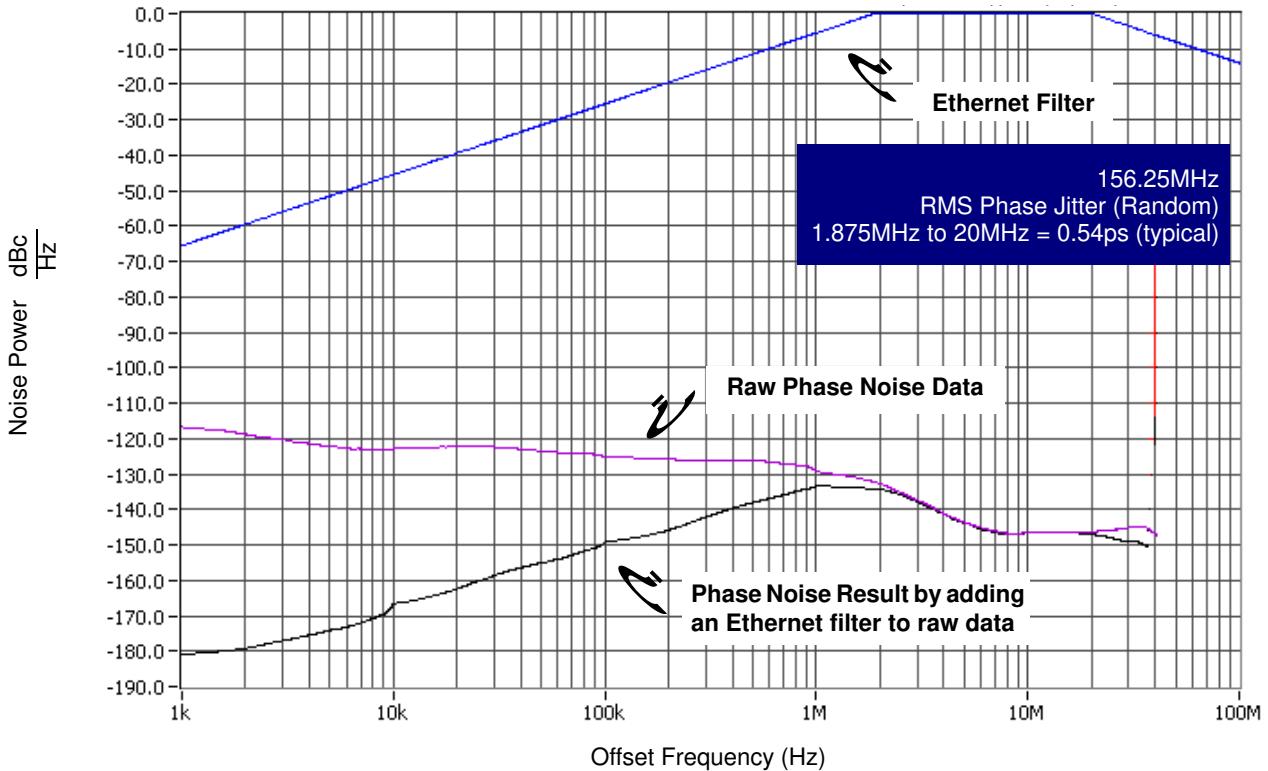Using a 25MHz, 18pF quartz crystal.
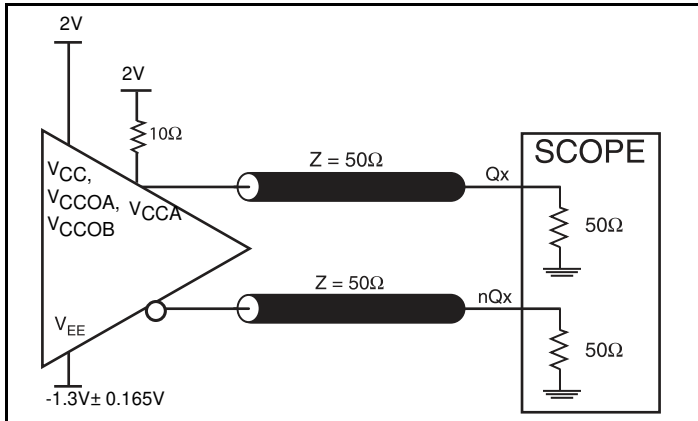NOTE 1: Please refer to the Phase Noise plots.

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Typical Phase Noise at 125MHz

125MHz
RMS Phase Jitter (Random)
1.875MHz to 20MHz = 0.56ps (typical)
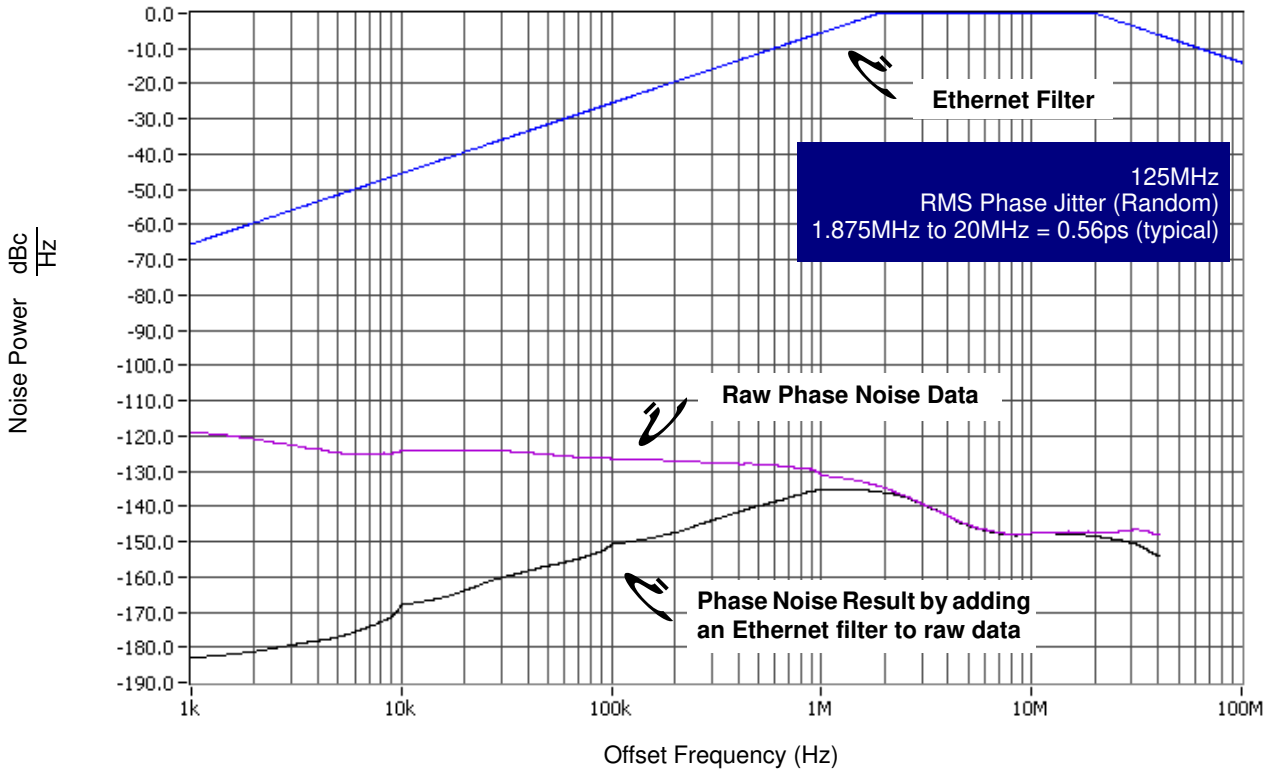
Typical Phase Noise at 156.25MHz

156.25MHz
RMS Phase Jitter (Random)
1.875MHz to 20MHz = 0.54ps (typical)

Parameter Measurement Information

3.3V LVPECL Output Load AC Test Circuit

$$\text{RMS Jitter} = \sqrt{\text{Area Under the Masked Phase Noise Plot}}$$
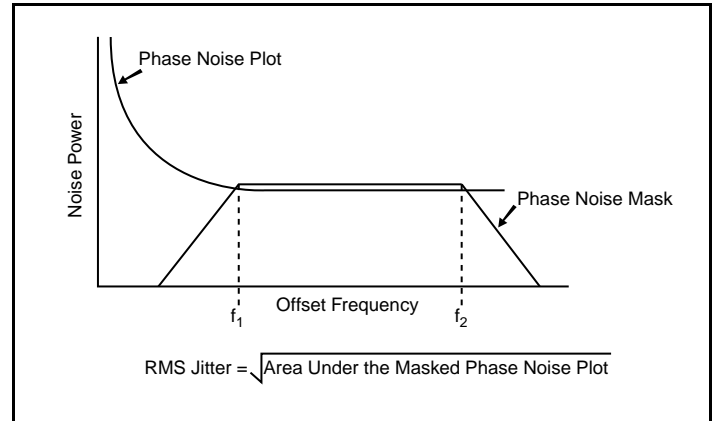
RMS Phase Jitter
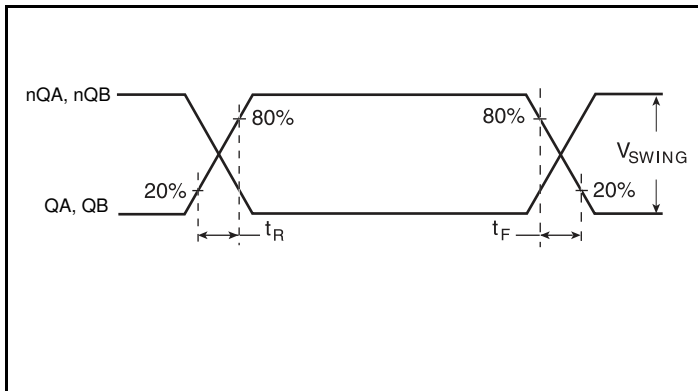
Output Rise/Fall Time

$$odc = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$
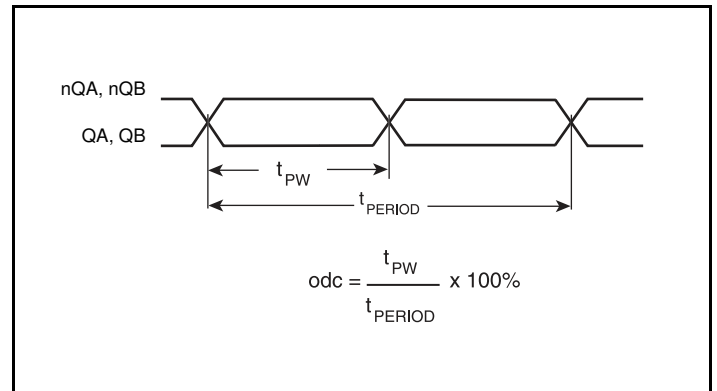
Output Duty Cycle/Pulse Width/Period

Application Information

Recommendations for Unused Input Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pullups; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

Outputs:

LVPECL Outputs

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The 843252-45 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{CC}, V_{CCA}, V_{CCOA}, and V_{CCOB} should be individually connected to the power supply plane through vias, and 0.01μF bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{CC} pin and also shows that V_{CCA} requires that an additional 10Ω resistor along with a 10μF bypass capacitor be connected to the V_{CCA} pin.
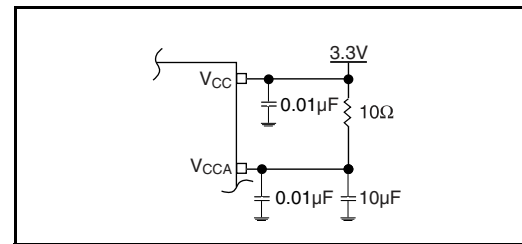

Figure 1. Power Supply Filtering

Crystal Input Interface

The 843252-45 has been characterized with 18pF parallel resonant crystals. The capacitor values, C1 and C2, shown in *Figure 2* below were determined using a 25MHz, 18pF parallel resonant crystal and were chosen to minimize the ppm error. The optimum C1 and C2 values can be slightly adjusted for different board layouts.
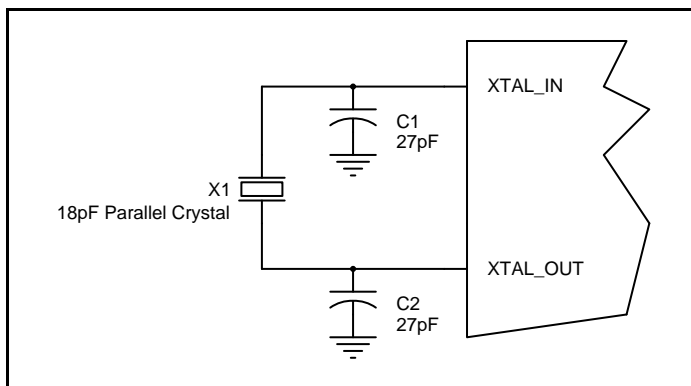

Figure 2. Crystal Input Interface

LVCMOS to XTAL Interface

The XTAL_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 3.* The XTAL_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output

impedance of the driver (Ro) plus the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most 50Ω applications, R1 and R2 can be 100Ω. This can also be accomplished by removing R1 and making R2 50Ω.
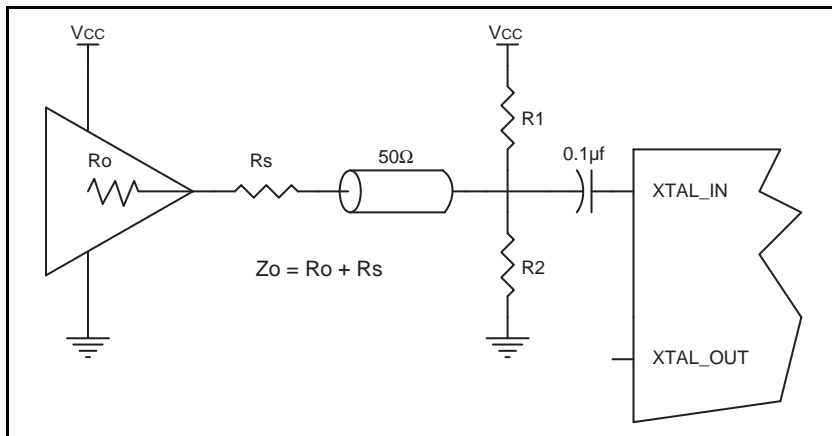

Figure 3. General Diagram for LVCMOS Driver to XTAL Input Interface

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω

transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 4A and 4B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.
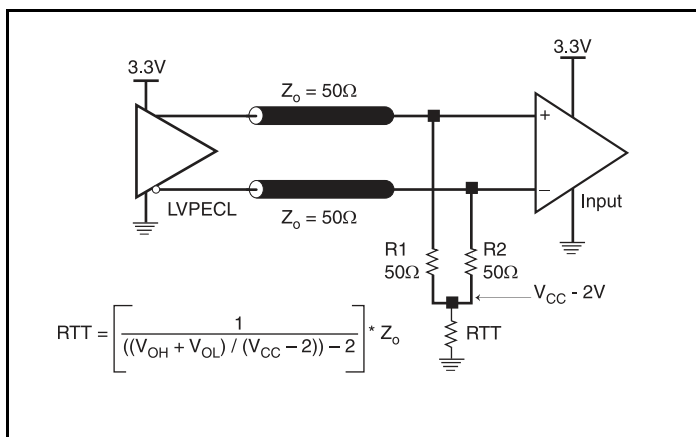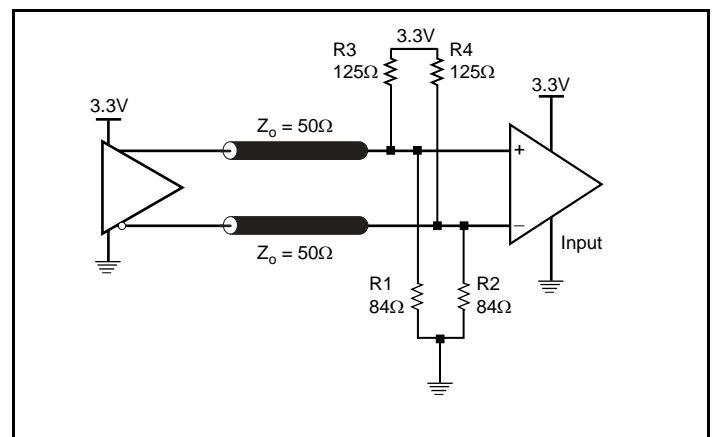

Figure 4A. 3.3V LVPECL Output Termination

Figure 4B. 3.3V LVPECL Output Termination

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Schematic Example

Figure 5 shows an example of 843252-45 application schematic. In this example, the device is operated at V_{CC} = 3.3V. The 18pF parallel resonant 25MHz crystal is used. The C1 = 27pF and C2 = 27pF are recommended for frequency accuracy. For different board layouts, the C1 and C2 may be slightly adjusted for optimizing frequency accuracy. Two examples of LVPECL terminations are shown in this schematic. Additional termination approaches are shown in the *LVPECL Termination Application Note.*
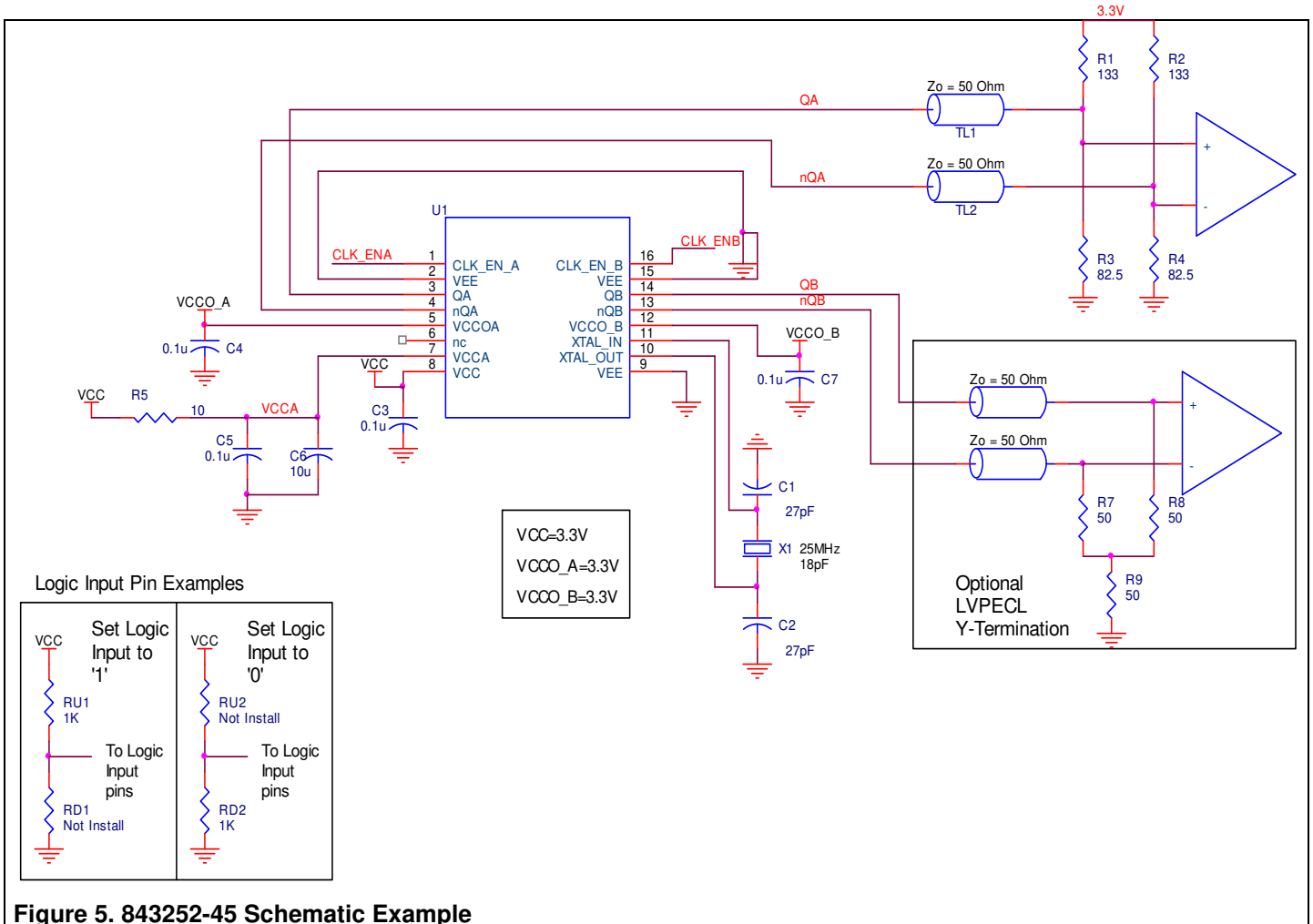

Figure 5. 843252-45 Schematic Example

Power Considerations

This section provides information on power dissipation and junction temperature for the 843252-45.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 843252-45 is the sum of the core power plus the power dissipated in the load(s).
The following is the power dissipation for V_{CC} = 3.3V + 5% = 3.465V, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)$_{MAX}$ = V_{CC_MAX} * I_{EE_MAX} = 3.465V * 75mA = **259.9mW**

- Power (outputs)$_{MAX}$ = **30mW/Loaded Output pair**
  If all outputs are loaded, the total power is 2 * 30mW = **60mW**

Total Power$_{\_MAX}$ (3.3V, with all outputs switching) = 259.9mW + 60mW = **319.9mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for Tj is as follows: $Tj = \theta_{JA}$ * Pd_total + T_A

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 92.4°C/W per Table 7 below.

Therefore, Tj for an ambient temperature of 70°C with all outputs switching is:

70°C + 0.320W * 92.4°C/W = 99.6°C. This is well below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 7. Thermal Resistance θ_{JA} for 16 Lead TSSOP, Forced Convection

θ_{JA} vs. Air Flow			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	92.4°C/W	88.0°C/W	85.9°C/W

3. Calculations and Equations.

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The purpose of this section is to derive the power dissipated into the load.

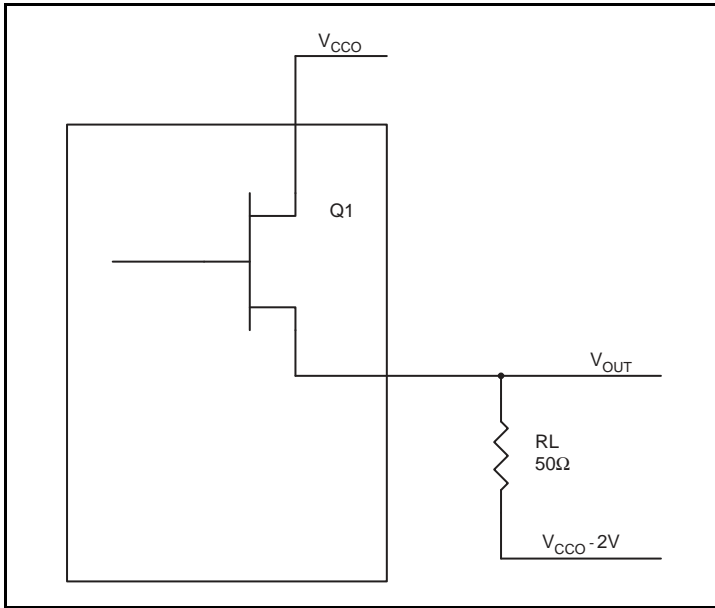LVPECL output driver circuit and termination are shown in *Figure 6.*

Figure 6. LVPECL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CCO} - 2V$.

- For logic high, $V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 0.9V$
  $(V_{CCO_MAX} - V_{OH_MAX}) = $ **0.9V**
- For logic low, $V_{OUT} = V_{OL\_MAX} = V_{CCO\_MAX} - 1.7V$
  $(V_{CCO_MAX} - V_{OL_MAX}) = $ **1.7V**

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$Pd_H = [(V_{OH_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - (V_{CCO_MAX} - V_{OH_MAX}))/R_L] * (V_{CCO_MAX} - V_{OH_MAX}) = [(2V - 0.9V)/50Ω] * 0.9V = $ **19.8mW**

$Pd_L = [(V_{OL_MAX} - (V_{CCO_MAX} - 2V))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - (V_{CCO_MAX} - V_{OL_MAX}))/R_L] * (V_{CCO_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50Ω] * 1.7V = $ **10.2mW**

Total Power Dissipation per output pair = Pd_H + Pd_L = **30mW**

Reliability Information

Table 8. θ_{JA} vs. Air Flow Table for a 16 Lead TSSOP

θ_{JA} vs. Air Flow			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	92.4°C/W	88.0°C/W	85.9°C/W

Transistor Count

The transistor count for 843252-45 is: 2039

Package Outline and Package Dimensions
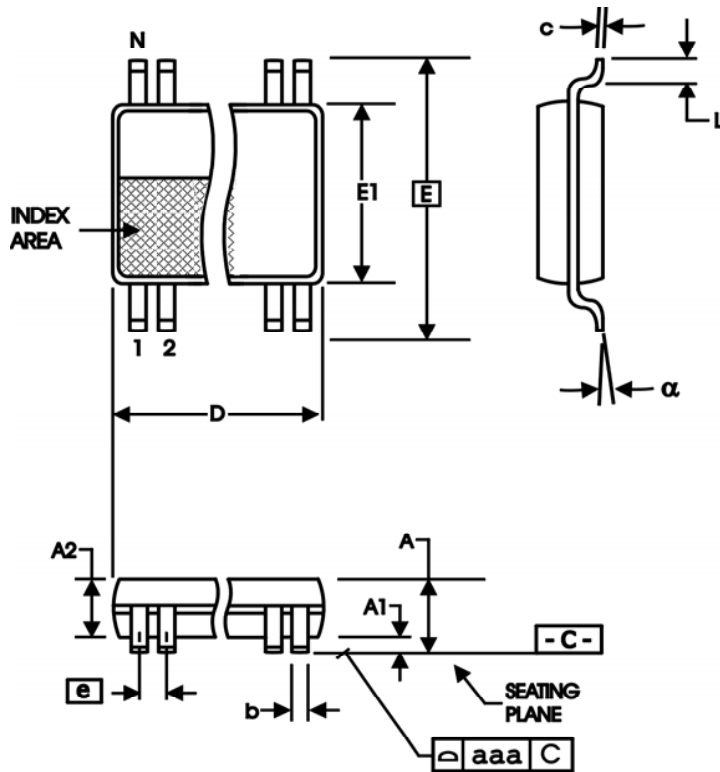
Package Outline - G Suffix for 16-Lead TSSOP

Table 9. Package Dimensions for 16 Lead TSSOP

All Dimensions in Millimeters		
Symbol	**Minimum**	**Maximum**
N	16	
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 10. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
843252AG-45LF	3252A45L	"Lead-Free" 16 Lead TSSOP	Tube	0°C to 70°C
843252AG-45LFT	3252A45L	"Lead-Free" 16 Lead TSSOP	Tape & Reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

Revision History Sheet

Rev	Table	Page	Description of Change	Date
A	T10	13	Ordering Information - removed leaded devices. Updated data sheet format.	5/28/15
A		1	Product Discontinuation Notice - Last time buy expires November 2, 2016. PDN# CQ-15-05	11/5/15
B			Obsolete datasheet per PDN# CQ-15-05. Updated datasheet header/footer.	11/7/16

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